

TOSHIBA**TMP8259AP**

TOSHIBA MOS TYPE DIGITAL
INTEGRATED CIRCUIT
Silicon Monolithic N-Channel Silicon Gate MOS

TMP8259AP
PROGRAMMABLE INTERRUPT CONTROLLER

1. GENERAL DESCRIPTION

TMP8259AP is a programmable interrupt controller. It handles up to eight vectored priority interrupts for the MPU. It is cascadable for up to 64 vectored priority interrupts without additional circuitry.

FEATURES

- Eight Level Priority Controller.
- Expandable to 64 Level.
- Interrupt Modes, Interrupt Mask, Vectored Address Programmable.
- Single +5V Power Supply.
- Supports 8085A, 8086 Microcomputer Interrupt Sequence.

2. PIN CONNECTIONS (TOP VIEW)

TMP8259AP

CS	1	28	VCC
WR	2	27	A ₀
RD	3	26	INTA
D ₇	4	25	IR ₇
D ₆	5	24	IR ₆
D ₅	6	23	IR ₅
D ₄	7	22	IR ₄
D ₃	8	21	IR ₃
D ₂	9	20	IR ₂
D ₁	10	19	IR ₁
D ₀	11	18	IR ₀
CAS ₀	12	17	INT
CAS ₁	13	16	SP / EN
VSS	14	15	CAS ₂

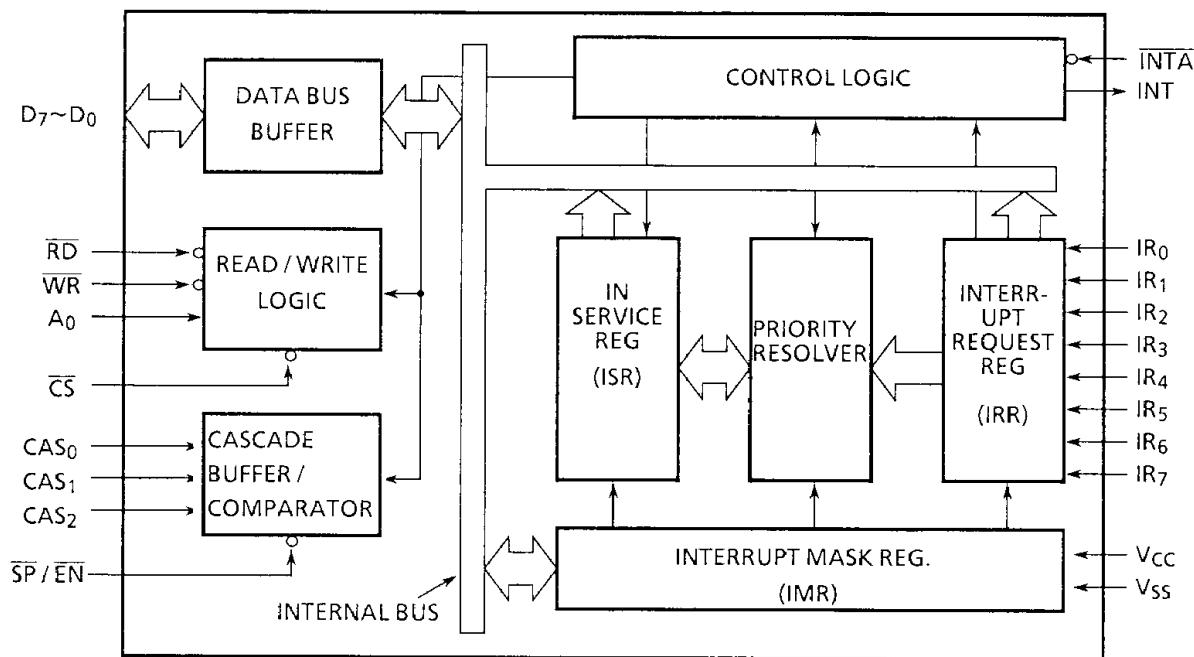
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3. PIN NAMES AND PIN DESCRIPTION

Pin Name	Input/Output	Function
\overline{CS}	Input	Chip Select Input. A low on this pin enables \overline{RD} and \overline{WR} communication between the MPU and the TMP8259AP. \overline{INTA} functions are independent of \overline{CS} .
\overline{WR}	Input	Write Control Input. A low on this pin when \overline{CS} is low enables the TMP8259AP to accept command words from MPU.
\overline{RD}	Input	Read Control Input. A low on this pin when \overline{CS} is low enables the TMP8259AP to release status onto the data bus for the MPU.
D ₀ to D ₇	Input/Output	Bidirectional Data Bus. Command status and interrupt-vector information is transferred via this bus.
CAS ₀ to CAS ₂	Input/Output	Cascade Lines. The CAS lines from a private TMP8259AP bus to control a multiple TMP8259AP structure. These pins are outputs for a master TMP8259AP and inputs for a slave TMP8259AP.
$\overline{SP} / \overline{EN}$	Input/Output	Slave Program / Enable buffer. This is a dual function pin. When in the buffered mode it can be used as an Output to control buffer transceivers (\overline{EN}). When not in the buffered mode it is used as an input to designate a master TMP8259AP ($\overline{SP} = 1$) or a slave ($\overline{SP} = 0$).
INT	Output	Interrupt Request Output. This pin goes high whenever a valid interrupt request is asserted. It is used to interrupt the MPU. It is connected to MPU's interrupt pin.
IR ₀ to IR ₇	Input	Interrupt Request Inputs. An interrupt request is executed by raising an IR input (low to high), and holding it high until it is acknowledged (Edge Triggered Mode), or just by a high level on a IR input (Level Triggered Mode.)
\overline{INTA}	Input	Interrupt Acknowledge INPUT. This pin is used to enable TMP8259AP interrupt-vector data onto the data bus by a sequence of interrupt acknowledged pulses issued by the MPU.
A ₀	Input	A ₀ address line. This pin acts in conjunction with the \overline{CS} , \overline{WR} and \overline{RD} pins. It is used by the TMP8259AP to decipher various command words the MPU writes and status the MPU wishes to read. It is typically connected to the MPU A ₀ address line.
VCC		+ 5V Power Supply
VSS		Ground

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4. BLOCK DIAGRAM



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5.1 ABSOLUTE MAXIMUM RATINGS

SYMBOL	ITEM	RATING
VCC	VCC Supply Voltage (with respect to VSS (GND))	-0.5 to + 7V
VIN	Input Voltage	-0.5 to + 7V
PD	Power Dissipation	1W
Tsol	Soldering Temperature (Soldering Time 10 sec)	260°C
Tstg	Storage Temperature	-65°C to + 150°C
Topr	Operating Temperature	0°C to 70°C

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5.2 DC CHARACTERISTICS

 $T_a = 0 \text{ to } + 70^\circ\text{C}$, $VCC = 5V \pm 10\%$, $Vss (\text{GND}) = 0V$

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VIL	Input Low Voltage		-0.5	—	0.8	V
VIH	Input High Voltage		2.2	—	$VCC + 0.5$	V
VOL	Output Low Voltage	$IOL = 2.2\text{mA}$	—	—	0.45	V
VOH	Output High Voltage	$IOH = -400\mu\text{A}$	2.4	—	—	V
VOH (INT)	Output High Voltage (INT)	$IOH = -100\mu\text{A}$	3.5	—	—	V
		$IOH = -400\mu\text{A}$	2.4	—	—	V
IIL	Input Leak Current	$0V \leq VIN \leq VCC$	—	—	± 10	μA
IIOFL	Output Leak Current	$0.45V \leq VIN \leq VCC$	—	—	± 10	μA
ILIR	Input Current (IR)	$VIN = 0V$	—	—	-300	μA
		$VIN = VCC$	—	—	10	μA
ICC	Operating Supply Current		—	—	85	mA

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5.3 INPUT CAPACITANCE

 $T_a = 25^\circ\text{C}$, $VCC = VSS$

SYMBOL	PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
CIN	INPUT CAPACITANCE	$f_C = 1 \text{ MHz}$ Unmeasured pins, 0V	—	—	10	pF
CI/O	INPUT / OUTPUT CAPACITANCE		—	—	20	pF

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5.4 AC CHARACTERISTICS

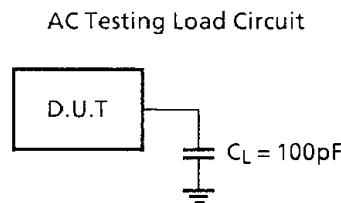
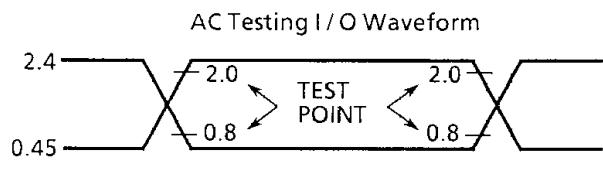
Ta = 0°C to + 70°C, VCC = 5V ± 10%, VSS = 0V

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
TAHRL	A ₀ / CS Setup Time (RD)		0	—	—	ns
TRHAX	A ₀ / CS Hold Time (RD)		0	—	—	ns
TRLRH	RD Pulse Width		235	—	—	ns
TAHWL	A ₀ / CS Setup Time (WR)		0	—	—	ns
TWHAX	A ₀ / CS Hold Time (WR)		0	—	—	ns
TWLWH	WR Pulse Width		290	—	—	ns
TDVWH	D ₀ to D ₇ Setup Time (WR)		240	—	—	ns
TWHDX	D ₀ to D ₇ Hold Time (WR)		0	—	—	ns
TJLJH	Input IR Low Level Pulse width (Edge Trigger Mode)		100	—	—	ns
TCVIAL	Cascade Setup Time (Second or Third INTA)		55	—	—	ns
TRHRL	RD to Next Command		160	—	—	ns
TWHWL	WR to Next Command		190	—	—	ns
*TCHCL	End of Command to next Command (Not Same)		500	—	—	ns
	End of INTA sequence to next INTA sequence					
TRLDV	Valid Data Delay (RD / INTA)	D ₇ to D ₀ CL = 100pF INT CL = 100pF CAS ₀ to 2 CL = 100pF	—	—	200	ns
TRHDZ	Data Floating (RD / INTA)		10	—	100	ns
TJHIH	Interrupt Output Delay (IR)		—	—	350	ns
TIALCV	Valid Cascade Delay (INTA)		—	—	565	ns
TRLEL	Enable Active (RD / INTA)		—	—	125	ns
TRHEH	Enable Inactive (RD / INTA)		—	—	150	ns
TAHDV	Valid Data Delay (A ₀ / CS)		—	—	200	ns
TCVDV	Valid Data Delay (CAS ₀ to CAS ₂)		—	—	300	ns

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* Worst case timing for TCHCL in an actual microprocessor system is typically much greater than 500 ns (i.e. 8085A = 1.6μs, 8085A-2 = 1μs, 8086 = 1μs, 8086-2 = 625μs)

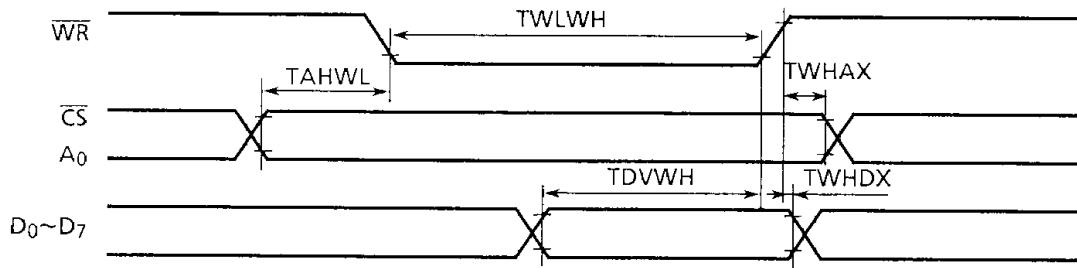
AC CHARACTERISTICS TEST CONDITION



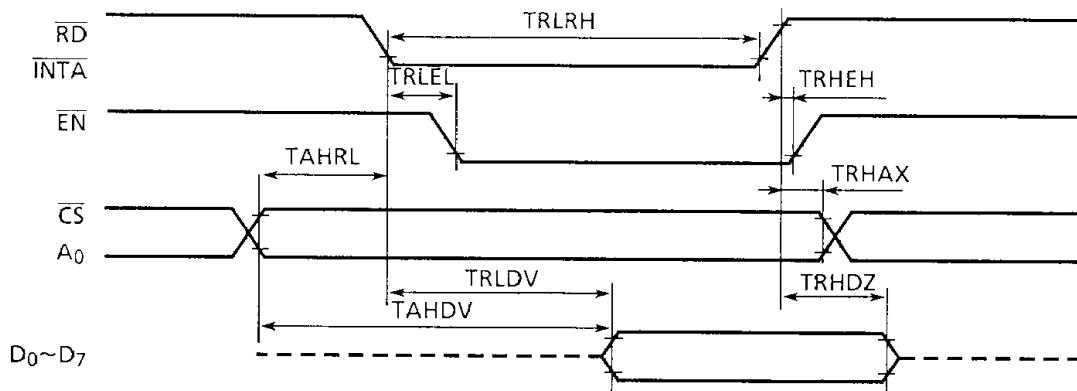
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6. TIMING WAVEFORMS

WRITE OPERATION

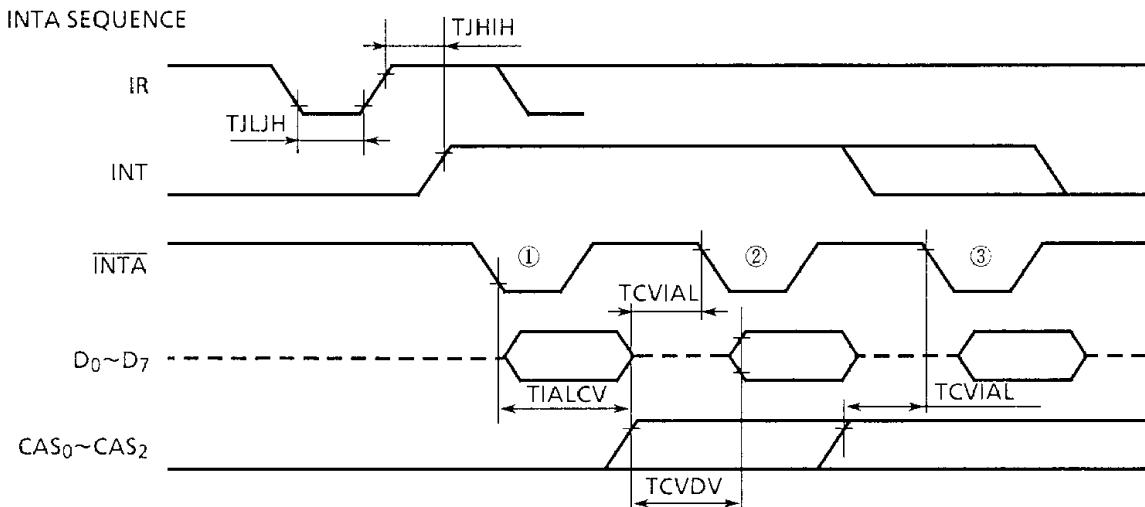


READ AND INTA OPERATION

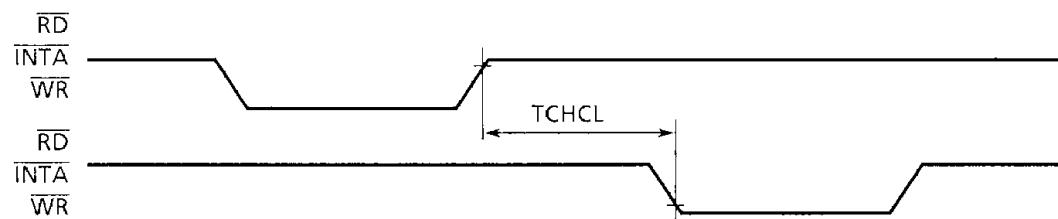
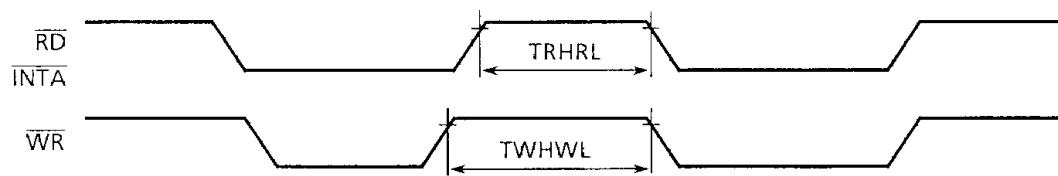


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INTA SEQUENCE



OTHER TIMING



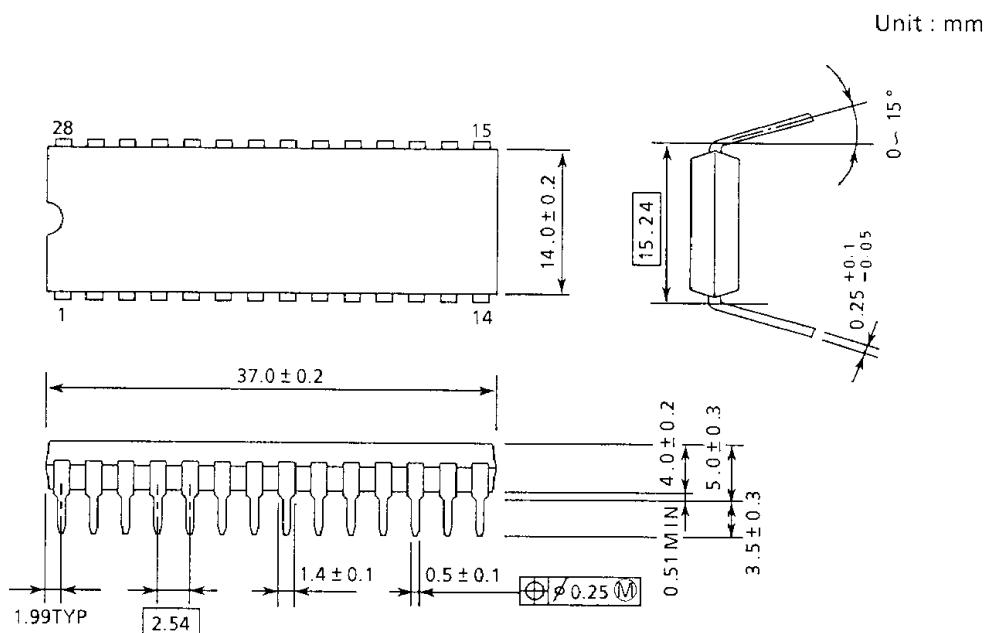
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7. EXTERNAL DIMENSION VIEW

28 pins PRASIC DIP

DIP28-P-600



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Note: Each lead pitch is 2.54mm, and all the leads are located within ± 0.25 mm from their theoretical position with respect to No.1 and No.28 leads.